

## Electronic Patent Application Fee Transmittal

Application Number:	10552540
Filing Date:	11-Oct-2005
Title of Invention:	Thermosetting resin composition, multilayer body using same, and circuit board
First Named Inventor/Applicant Name:	Shigeru Tanaka
Filer:	Troy M. Schmelzer/Firoozeh Vakilzadeh
Attorney Docket Number:	81844.0044

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>120</b>